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Attorney's Docket No.: 10417-031001 / S21-11638M/HW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Hisashi Shimizu et al.

Art Unit : 2814

Serial No. : 09/536898

Examiner : Wai-Sing Louie

Filed : March 28, 2000

Title : HYBRID INTEGRATED CIRCUIT DEVICE

Commissioner for Patents
Washington, D.C. 20231

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#7B Amtd N/E
M. Braunsen
8/29/02

RESPONSE

In response to the action mailed May 6, 2002, please amend the application as follows:

In the claims:

Please amend claims 8 and 15 as follows:

--8. (Twice Amended) A consolidated hybrid integrated circuit device according to claim 18 wherein said hybrid integrated circuit substrates are arranged in a matrix array and at least one end of said hybrid integrated circuit substrates is inclined at a predetermined angle with respect to a centrally located hybrid integrated circuit substrate.--

--15. (Twice Amended) A hybrid integrated circuit device comprising:
a hybrid integrated circuit substrate in which at least a surface is provided with insulation;
a first electrode and a second electrode formed on said surface;
a light emitting element connected with the first and second electrode;

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I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

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